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September 2001 Revised December 2001

FIN1022

2 X 2 LVDS High Speed Crosspoint Switch

General Description

This non-blocking 2x2 crosspoint switch has a fully differential input to output data path for low noise generation and low pulse width distortion. The device can be used as a high speed crosspoint switch, 2:1 multiplexer, 1:2 demultiplexer or 1:2 signal splitter. The inputs can directly interface with LVDS and LVPECL levels.

Features

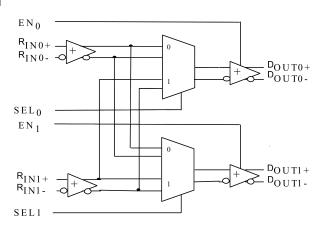
- Low jitter, 800 Mbps full differential data path
- Worst case jitter of 190ps with PRBS = 2²³ – 1 data pattern at 800 Mbps
- Rail-to-rail common mode range is 0.5V to 3.25V
- Worst case power dissipation is less than 126 mW
- Open-circuit fail safe protection
- Fast switch time of 1.1 ns typical
- 35 ps typical pin channel to channel skew
- 3.3V power supply operation
- Non-blocking switch
- LVDS receiver inputs accept LVPECL signals directly
- 7.5 kV HBM ESD protection
- 16-lead SOIC package and TSSOP package
- Inter-operates with TIA/EIA 644-1995 specification
- See the Fairchild Interface Solutions web page for cross reference information: www.fairchildsemi.com/products/interface/lvds.html

Ordering Code:

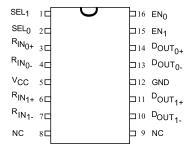
Order Number	Package Number	Package Description
FIN1022M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
FIN1022MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code

Logic Symbol



Connection Diagram



Pin Descriptions

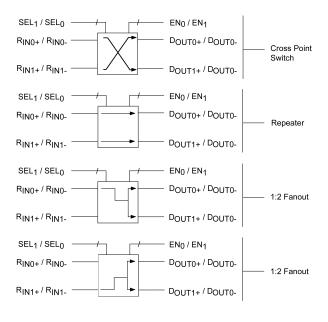
Pin Name	Description
R _{IN0+} , R _{IN1+}	LVDS non-inverting data inputs
R _{IN0-} , R _{IN1-}	LVDS inverting data inputs
D_{OUT0+},D_{OUT1+}	LVDS non-inverting data outputs
D_{OUT0-}, D_{OUT1-}	LVDS inverting data outputs
EN ₀	LVTTL input for enabling D _{OUT0+} /D _{OUT0-}
EN ₁	LVTTL input for enabling D _{OUT1+} /D _{OUT1-}
SEL ₀	LVTTL input for selecting R_{IN0+}/R_{IN0-} or R_{IN1+}/R_{IN1-} for output D_{OUT0+}/D_{OUT0-}
SEL ₁	LVTTL input for selecting R_{IN0+}/R_{IN0-} or R_{IN1+}/R_{IN1-} for output D_{OUT1+}/D_{OUT1-}
V _{CC}	Power Supply
GND	Ground

Function Table

Inputs			Outputs			Mode		
SEL ₀	SEL ₁	EN ₀	EN ₁	D _{OUT0+}	D _{OUT0-}	D _{OUT1+}	D _{OUT1-}	Wode
L/O	L/O	Н	Н	R _{IN0+}	R _{IN0-}	R _{IN0+}	R _{IN0-}	1:2 Splitter
L/O	Н	Н	Н	R _{IN0+}	R _{IN0-}	R _{IN1+}	R _{IN1}	Repeater
Н	L/O	Н	Н	R _{IN1+}	R _{IN1-}	R _{IN0+}	R _{IN0-}	Switch
Н	Н	Н	Н	R _{IN1+}	R _{IN1-}	R _{IN1+}	R _{IN1-}	1:2 Splitter
Х	L/O	L/O	Н	Z	Z	R _{IN0+}	R _{IN0-}	D _{OUT0} Disabled
X	Н	L/O	Н	Z	Z	R _{IN1+}	R _{IN1-}	D _{OUT0} Disabled
L/O	Х	Н	L/O	R _{IN0+}	R _{IN0-}	Z	Z	D _{OUT1} Disabled
Н	Х	Н	L/O	R _{IN1+}	R _{IN1-}	Z	Z	D _{OUT1} Disabled
X	Х	L/O	L/O	Z	Z	Z	Z	D _{OUT0} and D _{OUT1} Disabled
OPEN	L / O = LOV	V or OPEN	H = HI	GH Logic Lev	vel L=	LOW Logic	Level	X = Don't Care Z = High Impeda

Z = High Impedance

Function Diagrams



Absolute Maximum Ratings(Note 1)

(Soldering, 10 seconds) 260°C

Recommended Operating Conditions

 $\begin{array}{lll} \mbox{Supply Voltage (V_{CC})} & 3.0 \mbox{V to } 3.6 \mbox{V} \\ \mbox{Input Voltage (V_{IN})} & 0 \mbox{ to } \mbox{V}_{CC} \\ \mbox{Operating Temperature (T_A)} & -40 \mbox{°C to } +85 \mbox{°C} \\ \end{array}$

Electrostatic Discharge

(HBM 1.5 kΩ, 100 pF) >7500V

Electrostatic Discharge

(MM 0Ω , 100 pF) >300V

Note 1: The "Absolute Maximum Ratings": are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature and output/input loading variables. Fairchild does not recommend operation of circuits outside databook specification.

DC Electrical Characteristics

Over supply voltage and operating temperature ranges, unless otherwise specified (Note 2)

Symbol	Parameter	Test Conditions	Min	Typ (Note 3)	Max	Units	
LVDS Diffe	rential Driver Characteristics						
V _{OD}	Output Differential Voltage	$R_L = 75 \Omega$, See Figure 3	270	365	475		
		R_L = 75 Ω, See Figure 3 T_A = 25°C and V_{CC} = 3.3V	285	365	440	mV	
ΔV_{OD}	V _{OD} Magnitude Change from Differential LOW-to-HIGH	$R_L = 75 \Omega$, See Figure 3			35	mV	
Vos	Offset Voltage	See Figure 3	1.0	1.2	1.45	V	
ΔV_{OS}	Offset Magnitude Change from Differential LOW-to-HIGH	See Figure 3			35	mV	
I _{OZD}	Disabled Output Leakage Current	V _{OUT} = 3.6V or GND, Driver Disabled			±10	μΑ	
I _{OFF}	Power-Off Current	$V_{CC} = 0V$, V_{IN} or $V_{OUT} = 3.6V$ or $0V$			±20	μΑ	
Ios	Short Circuit Output Current	V _{OUT} = 0V, Driver Enabled			-10		
		V _{OUTx+} = 0V, V _{OUTx-} = 0V, Driver Enabled			-10	mA	
LVDS Diffe	rential Receiver Characteristics						
V _{TH}	Differential Input Threshold HIGH	V _{IC} = 0.05V or 1.2V or 3.25V			100	mV	
V_{TL}	Differential Input Threshold LOW	V _{CC} = 3.3V	-100			IIIV	
V _{IC}	Input Common Mode Voltage		0.05		3.25	V	
I _{IND}	Input Current (Differential Inputs)	V _{IN} = GND			±20		
	1	$V_{IN} = V_{CC}$			±20	μΑ	
LVTTL Con	trol Characteristics						
V _{IH}	Input High Voltage		2			V	
V _{IL}	Input Low Voltage				0.8	V	
I _{IN}	Input Current	V _{IN} = 3.6V or GND			±20	μΑ	
Device Cha	aracteristics						
V _{IK}	Input Clamp Voltage	$I_{IK} = -18 \text{ mA}$	-1.5			V	
I _{PU/PD}	Output Power-Up/Power-Down High Z Leakage Current	V _{CC} = 0V to 1.5V			±10	μА	
C _{IN}	Input Capacitance			4.5		pF	
C _{OUT}	Output Capacitance			4.5		pF	
I _{CC}	Power Supply Current	No Load, All Drivers Enabled			35	mA	
		$R_L = 75 \Omega$, All Drivers Enabled			35	mA	
		$R_L = 75 \Omega$, All Drivers Enabled			35	mA	

Note 2: This part will only function with datasheet specification when a resistive load is applied to the driver outputs.

Note 3: All typical values are at $T_A=25^{\circ}C$ and with $V_{CC}=3.3V.$

AC Electrical Characteristics

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ (Note 4)	Max	Units
t _{PLHD}	Differential Output Propagation Delay		0.7		1.6	no
	LOW-to-HIGH	$R_L = 75 \Omega, C_L = 5 pF,$	1.0	1.2	1.3	ns
t _{PHLD}	Differential Output Propagation Delay	V _{CC} = 3.3V, T _A = 25°C	0.7		1.6	ns
	HIGH-to-LOW	See Figure 4 and Figure 5	1.0	1.2	1.3	115
t _{TLHD}	Differential Output Rise Time (20% to 80%)	1	290		580	ps
t _{THLD}	Differential Output Fall Time (80% to 20%)		290		580	ps
t _{PLH}	Selection Propagation Delay		0.6		1.5	ns
	LOW-to-HIGH (SEL _n to OUT _n)	$R_L = 75 \Omega, C_L = 5 pF,$	0.9	1.1	1.2	ns
t _{PHL}	Selection Propagation Delay	V _{CC} = 3.3V, T _A = 25°C	0.6		1.5	
	HIGH-to-LOW (SEL _n to OUT _n)	See Figure 6 and Figure 7	0.9	1.1	1.2	ns
t _{ZHD}	Differential Output Enable Time				3.5	
	from Z-to-HIGH				3.3	ns
t _{ZLD}	Differential Output Enable Time	1			3.5	
	from Z-to-LOW	$R_L = 75\Omega$, $C_L = 5 pF$			3.3	ns
t _{HZD}	Differential Output Disable Time	See Figure 8 and Figure 9			3.5	ns
	from HIGH-to-Z				3.3	115
t _{LZD}	Differential Output Disable Time	1			3.5	ns
	from LOW-to-Z				3.3	115
t _{SET}	Input (IN _{n+} /IN _{n-}) Setup Time to SEL _n	See Figure 10	0.5	0.3		ns
t _{HOLD}	Input (IN _{n+} /IN _{n-}) Hold Time to SEL _n	See Figure 10	0.5	0.3		ns
t _{JIT}	Output Peak-to-Peak Jitter	2 ²³ –1 PRBS Sequence at 800 Mbps			190	ps
		50% Duty Cycle at 800 Mbps		20	35	ps
f _{TOG}	Maximum Toggle Frequency	$R_L = 75 \Omega$, $C_L = 5 pF$, See Figure 4	800	900		Mbps
t _{SKEW}	Within Device Channel-to-Channel Skew			35	80	ps
	Pulse Skew t _{PLHD} -t _{PHLD}			0	225	ps
	Part-to-Part Skew (Note 5)			100	500	ps

Note 4: All typical values are at $T_A = 25^{\circ}\text{C}$ and with $V_{CC} = 3.3\text{V}$.

Note 5: Part-to-part skew is the maximum delay time difference on like edges (LOW-to-HIGH or HIGH-to-LOW) for the same V_{CC} and temperature conditions.

Required Specifications

- 1. When the true and complement LVDS outputs (having a 75 Ω connected between outputs) are connected to 3.75 k Ω resistors and the common point of those 3.75 k Ω resistors are connected to a voltage source that sweeps from 0 to 2.4V, the DC V_{OD} and Δ V_{OD} are still maintained (see Figure 1).
- 2. When the true and complement LVDS outputs (having a 5 pF capacitor attached between outputs) are connected with 37.5 Ω resistors each to common point, then the common point does not vary by more than 150 mV under all process, temperature and voltage conditions when the outputs switch either from LOW-to-HIGH or from HIGH-to-LOW (see Figure 2).
- Pull-down resistors are required on Enable (EN₀ and EN₁) and select (SEL₀ and SEL₁) inputs.
- 4. Fail safe protection on the outputs that draw less than 20 μA of current (worst case) on the LVDS inputs. In this condition, if the input is in fail safe selected to $\text{OUT}_{0+}/\text{OUT}_{0-}$ (say) and the outputs are Enabled then $\text{OUT}_{0+}=\text{HIGH}$ and $\text{OUT}_{0-}=\text{LOW}.$ This prevents noise from being amplified when the connection is broken.
- 5. In the disabled state the outputs can go beyond V_{CC} but there should be no appreciable leakage (see I_{OZD} and I_{OFF} specifications)

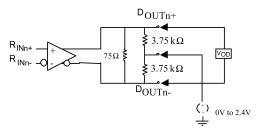


FIGURE 1. Common Mode Supply Test Circuit

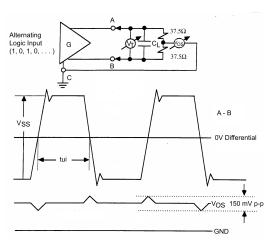


FIGURE 2. Dynamic \mathbf{V}_{OS} Test Circuit and Waveforms

Required Specifications (Continued)

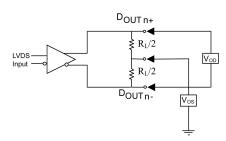
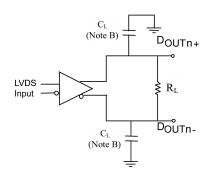


FIGURE 3. LVDS Driver DC Test Circuit



Note A: All input pulses have frequency = 50 MHz, t_R or t_F = 500 ps Note B: C_L includes all probe and jig capacitances

FIGURE 4. LVDS Input to LVDS Driver Propagation Delay and Transition Time Circuit

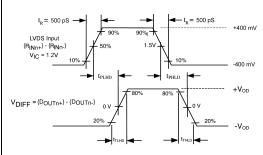


FIGURE 5. LVDS Input to LVDS Output AC Waveforms

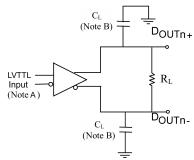
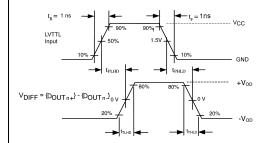
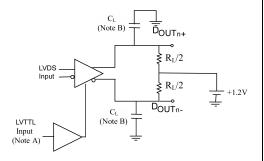


FIGURE 6. LVTTL Input to LVDS Driver Propagation Delay and Transition Time Test Circuit

Required Specifications (Continued)





Note A: All input pulses have frequency = 10MHz, t_R or t_F < = 1 ns. Note B: C_L includes all probe and jig capacitances.

FIGURE 7. LVTTL Input to LVDS Output AC Waveforms

FIGURE 8. Differential Driver Enable and Disable Test Circuits

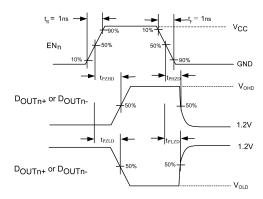
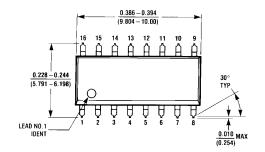


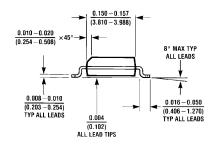
FIGURE 9. Enable and Disable AC Waveforms

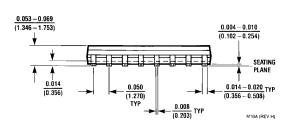
Required Specifications (Continued) Valid data output Invalid Data Output -SET--SET-Select Select R_{IN+} R_{IN} + D_{OUT+} D_{OUT+} — tPLH -- tPLH Valid data output Invalid Data Output HOLD HOLD Select Select R_{IN+} R_{IN+} DOUTH $D_{\mbox{OUT+}}$ — tPLH-— t_{PLH}— Undefined State

FIGURE 10. Set-up and Hold Time Specification

Physical Dimensions inches (millimeters) unless otherwise noted







16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M16A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 7.72 TYP. DIMENSIONS METRIC ONLY (1.78 TYP) 0.42 TYP LAND PATTERN RECOMMENDATION GAGE PLANE 6.4 0.25 4.4 ± 0.1 -B-3.2 SEATING PLANE 0.6 ± 0.1 DETAIL A TYPICAL, SCALE: 40X △ 0.2 C B A ALL LEAD TIPS PIN #1 IDENT SEE DETAIL A (0.90)□ 0.1 C ALL LEAD TIPS -C-0.65 TYP 0.10 ± 0.05 TYP 0.09-0.20 TYP

16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC16

A BS

c (S)

0.30 TYP

0.13 M

Ф

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